/ Descriptions

TO-263 ĮĮĖ N ŏs MOS ĵ ŵ Ẓ ˥ N-CHANNEL MOSFET in a TO-263 Plastic Package.

/ Features

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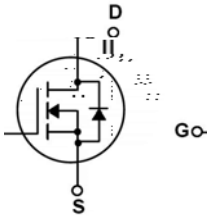
Low gate charge, low crss, fast switching.

/ Applications

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These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

/ Equivalent Circuit



/ Pinning



PIN1 χ G PIN 2,4 χ D PIN 3 χ S

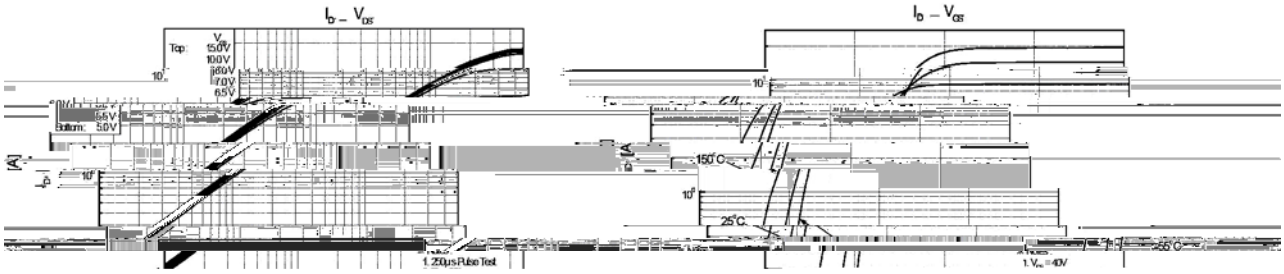
/ h_{FE} Classifications & Marking

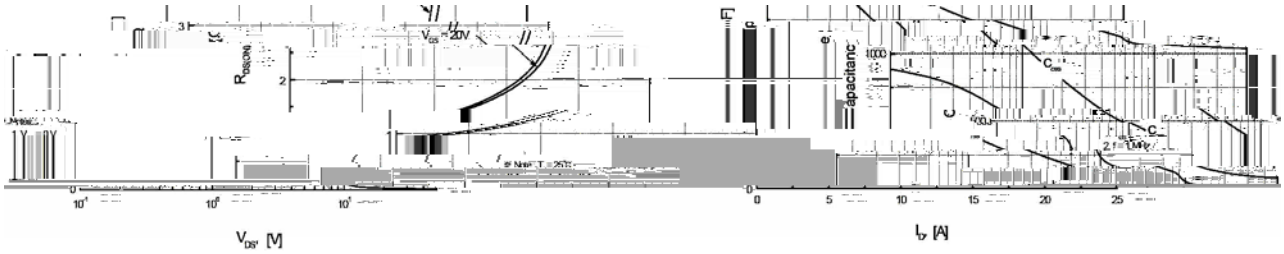
ȏ ᴍ ˥ ب ˝ See Marking Instructions.

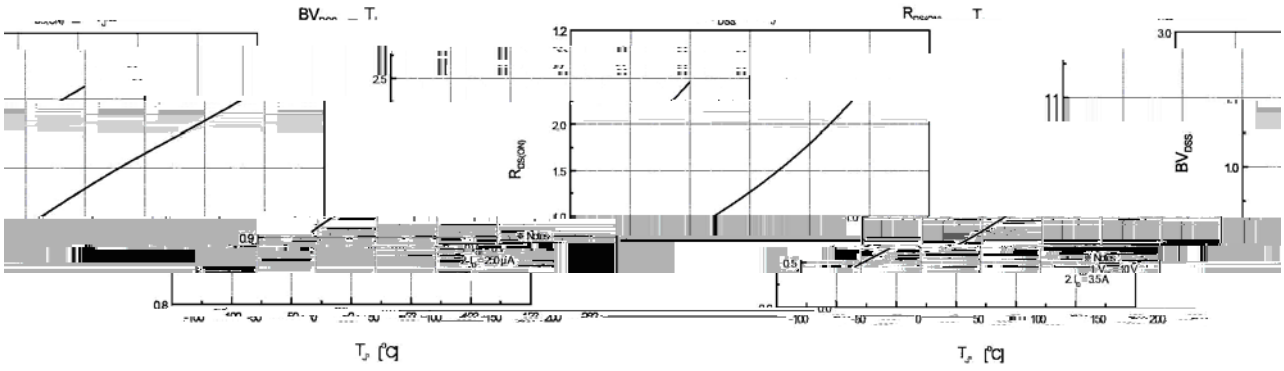
v ̈Ω Parameter	ϒ N Symbol	̈Ω Ö Rating	D Ч Unit
Drain-Source Voltage	V_{DSS}	650	V
Drain Current	I_D(Tc=25)	7.0	A
Drain Current	I_D(Tc=100)	4.4	A
Drain Current - Pulsed	I_{DM}	28	A
Gate-Source Voltage	V_{GS}	±30	V
Single Pulsed Avalanche Energy	E_{AS}	420	mJ
Repetitive Avalanche Energy	E_{AR}	14.7	mJ
Avalanche Current	I_{AR}	7.0	A
Power Dissipation	P_D(Tc=25)	147	W
Operating and Storage Temperature Range	T_J,T_{STG}	-55 to 150	

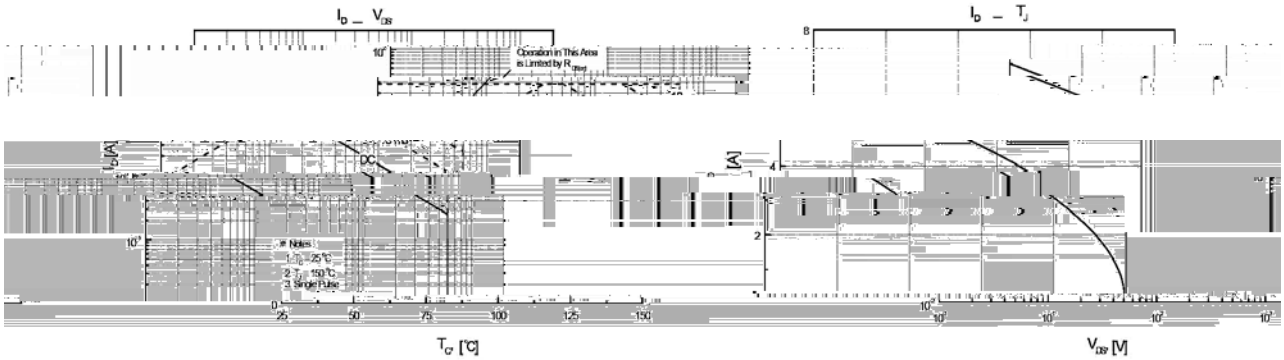
v ̈Ω Parameter	ϒ N Symbol	Ш :ϯ Ţ Test Conditions	ώ ή Ö Min	Ɛ ʒ Ö Typ	ώ ƶ Ö Max	D Ч Unit
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250 A	650			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=650V V_{GS}=0V			1.0	A
		V_{DS}=520V T_C=125			100	A
Gate-Body Leakage Current Forward	I_{GSS}	V_{GS}=±30V V_{DS}=0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} I_D=250 A	2.0		4.0	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V I_D=3.5A			1.3	
Forward Transconductance	g_{FS}	V_{DS}=40V I_D=3.5A		8.2		S
Drain-Source Diode Forward Voltage	V_{SD}	V_{GS}=0V I_S=7.0A			1.4	V

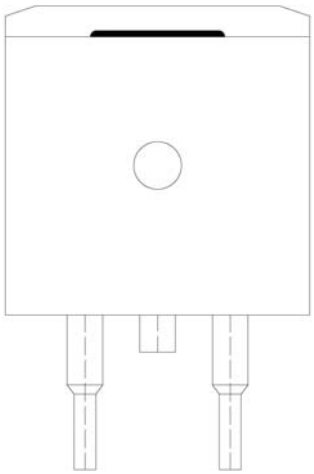
/ Electrical Characteristic Curve









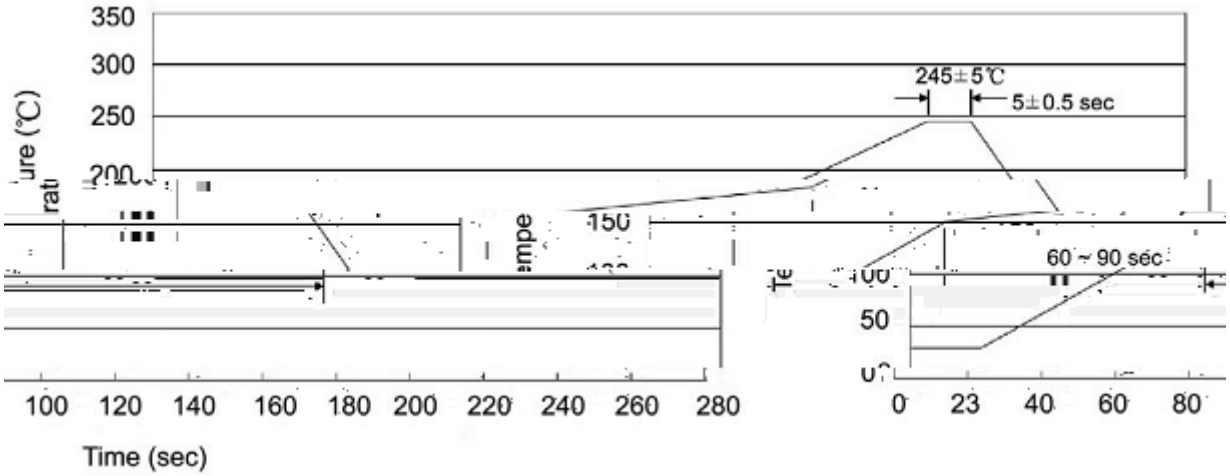


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BR χ	ѭ ϗ Ͷ Ղ
7N65 χ	ѭ ϓ ᴺ Ղ
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Note:

BR:	Company Code
7N65:	Product Type.
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



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1 Ĺ ♬ □ ỷ 25 Ḱ 150 ł ı ˋH ڑ 60 Ḱ 90sec;

2 Š Ë □ ỷ 245 ° 5 ł ı ˋH ڑ ˋY ﾊ ㎞ 5 ° 0.5sec;

3 ì ˙ ｲ ˛ ɔ ﻉ ỷ ㎞ 2 Ḱ 10 ł /sec.

Note:

1.Preheating:25~150 ł , Time:60~90sec.

2.Peak Temp.:245 ° 5 ł , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ł /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ł ˋH ڑ χ 10 ° 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ɔ ` ｙ Ł / REEL

Package Type	Units					Dimension (unit mm³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13 ×24	360×360×50	385×257×392

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